

# Clean Track ACT 8 System Inspection List

## Machine Specifications

**Product :** Clean Track System

**Model :** ACT-8 In-line System

**Serial No. :** \_\_\_\_\_

- |  |   |   |  |  |  |
|--|---|---|--|--|--|
| <input checked="" type="checkbox"/> In-line              | <input type="checkbox"/> Local                      | <b>2COAT 2DEV</b>                                     |  |  |  |
| <input checked="" type="checkbox"/> CSB                  | <input checked="" type="checkbox"/> PRB1            | <input type="checkbox"/> PRB2                         | <input checked="" type="checkbox"/> IFB    |  |  |
| <input type="checkbox"/> Transformer                     | <input checked="" type="checkbox"/> Power Box       | <input checked="" type="checkbox"/> T&H Controller #1 | <input type="checkbox"/> T&H Controller #2 |  |  |
| <input checked="" type="checkbox"/> Chemical Box #1      | <input checked="" type="checkbox"/> Chemical Box #2 | <input type="checkbox"/> Chemical Box #3              | <input type="checkbox"/> Chemical Box #4   |  |  |
| <input checked="" type="checkbox"/> Thermo Controller #1 | <input type="checkbox"/> Fire System Box#1          | <input type="checkbox"/> Fire System Box#2            | <input type="checkbox"/> Fire System Box#3 |  |  |

## 2. Machine Configuration :

1-3 SUC	1-0 CRA	2-24 HSL	2-29 HHP	2-14 HSL	3-4 WEE
		2-23 PCH	2-28 HHP	2-13 HSL	
		2-22 PCH		2-12 CPL	
			2-11 CPL	3-0 IRA	
			2-10 CWH 2- 9 CPL		
2-7 ADH		2-0 PRA	2-17 ADH		
2-6 TRS			2-16 TRS		
2-5 TCP			2-15 CPL		
1-2 SUC		2-3 DEV	2-4 DEV	3-3 SBU 3-2 SBU 3-1 THS	
		2-1 COT	2-2 T.L COT		

## 3. Overall Status :

Existed Machine Status    ☐ Running ☒ Idle ☐ Disconnected ☐ Facility Removed

Power System Status        ☒ On        ☐ Off        ☐ Disconnected

Gas System Status            ☒ On        ☐ Off        ☐ Disconnected

C.S.S System Status         ☐ On        ☐ Off        ☒ Disconnected

## 4. Machine Detail Check

### 1. DESCRIPTION

- 1-1. Number of Machine :
- 1-2. Left to Right
- 1-3. Model : Clean track ACT-8
- 1-4. Wafer & Carrier Type : 8", Notch Type , 25 Slots
- 1-5. System Power Rating : AC 208V , 3-Phase for System , 200A(MAX)
- 1-6. Loading Configuration : SMIF 3 Loader Unicassete
- 1-7. Software Version : 2.3.0
- 1-8. Main Controller : #2 Controller

### 2. Main System

1) Main Frame with System Controller

2) Carrier Station

- Type : SMIF Cassette Type
- 3 Cassette / 25 slots

3) Coater unit

2-1 Coater

- 8 Dispense Nozzle with Temperature Controlled Lines for Each Unit
- 6 Dispense RDS Pump
- Rinse Nozzle : RRC / Back Rinse1,2 / EBR / Solvent Bath / Drain Case Cleaning For Each Unit
- PR Suck Back Valve : Auto Suck Back Valve(6ea)

## 2-2 T.L Coater

- 4 Dispense Nozzle with Temperature Controlled Lines for Each Unit
- 2 Dispense RDS Pump
- Rinse Nozzle : Back Rinse1,2 / EBR / Solvent Bath / Drain Case Cleaning For Each Unit
- PR Suck-back Valve : Auto Suck Back Valve(2ea)
- Rinse System : 3 Liter 2 Buffer Tank System
- Programmable Side Rinse
- Solvent Supply : CCSS
- Degassing System
- Drain : Manual Drain (With Drain Pump & Drain Level Sensor) & Drain Tank(20 Liter)

4) Developer unit(2-3,2-4 )

- LD Nozzle(1EA) with Temperature Controlled for Each Unit
- 1 Stream Nozzle for DI Rinse and 2 Points for Back Side Rinse on Each Unit
- Developer System : 3 Liter 2 Buffer Tank System
- Developer Supply : CCSS
- Degassing system
- Developer Temperature Control System
- Drain: Direct Drain

5) I/F Wafer Stage Type : Nikon

## 6) Adhesion Unit

- 100% Sealing Closed Chamber(Built-in Hot Plate)
- HMDS Tank with Float Sensor in System
- HMDS Supply : Local Canister
- Temperature Range : 50.0 ~ 180 °C(set in a minimum unit of 0.1 °C)
- Plant Temperature Accuracy : 
 

50.0 ~ 120.0 °C	R ≤ 0.4 °C
120.1 ~ 150.0 °C	R ≤ 0.8 °C
150.1 ~ 180.0 °C	R ≤ 1.2 °C

## 7) High Speed Low Temp Hot Plates (HSL)

### 8) High Temp Hot Plates (HHP)

- Temperature Range : 50.0 ~ 350.0 °C (set in a minimum unit of 0.1 °C)
- Plant Temperature Accuracy :

50.0 ~ 120.0 °C	R ≤ 1.2 °C
120.1 ~ 150.0 °C	R ≤ 1.7 °C
150.1 ~ 200.0 °C	R ≤ 2.2 °C
200.1 ~ 300.0 °C	R ≤ 3.5 °C
300.1 ~ 350.0 °C	R ≤ 6.0 °C

### 9) Chill Plate Process Station (CPL)

- Temperature Range : 15.0 ~ 30.0 °C (set in a minimum unit of 0.1 °C)
- Plant Temperature Accuracy : 15.0 ~ 30.0 °C      $R \leq 0.2$  °C

### 10) Precision Chilling Hot Plate Process Station(PCH)

- Temperature Range : 50.0 ~ 200.0 °C (set in a minimum unit of 0.1 °C)
- Plant Temperature Accuracy :
 

90.0 ~ 120.0 °C	$R \leq 0.2$ °C
120.1 ~ 150.0 °C	$R \leq 0.3$ °C
150.1 ~ 200.0 °C	$R \leq 0.5$ °C

11) Transtation Chill plate(TCP)

## 12) Transtation Stage(TRS)

- 13) Wafer Edge Exposure Process Station(WEE)
  - Wafer Type : Notch
- 14) Chemical Cabinet 1 : Photo Resist
- 15) Chemical Cabinet 2 : Develop & Solvent & HMSD
- 16) Temperature & Humidity Controller
  - Type: SHINWA(TEL OEM)
- 17) TEMP Control Unit(TCU)
  - Type : TEL OEM
- 18) AC Power Box
  - AC200/220V , Full-load Current 125A